Supply Chain Explorer

By the Emerging Technology Observatory

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CMP materials

Chemical mechanical planarization (CMP) is a process that makes layers produced during fabrication flat so lithography can successfully be performed on them. The highest-value materials used in chemical mechanical planarization are chemical slurries, which often include rare earth minerals, and polishing pads. During fabrication, a wafer is placed on the pad along with the slurry, and a polishing head presses against the wafer and rotates to planarize the wafer.

Country provision

- China (mainland)
- France
- Japan
- · United States

Notable supplier companies

- Anji China (mainland)
- · CMC United States
- DuPont United States
- Fujifilm Electronic Materials Japan
- Fujimi Japan
- · Hitachi Japan
- Hubei Dinglong China (mainland)
- JSR Japan
- Merck Group Germany
- · Pureon United States
- Saint-Gobain France
- · Thomas West United States
- · Versum Materials United States